



E-Song America, Inc.

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THERMAL INTERFACE PAD: THEA715UC2, 2-Parts Gel Pad

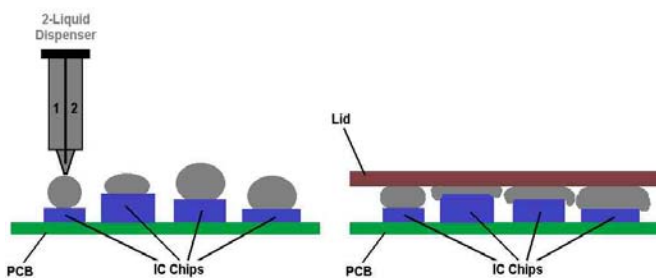
■ Characteristic

This product comes uncured in 2 parts. Once mixed 1:1, the mixture cures in less than 5 min. at 100°C, 6.5 min at 85°C or in 12 hours at room temp. Shrinkage when cured is negligible. Once cured, it becomes a solid but soft pad, providing high thermal conductivity and cushion. Flame retardant and electrical insulator.

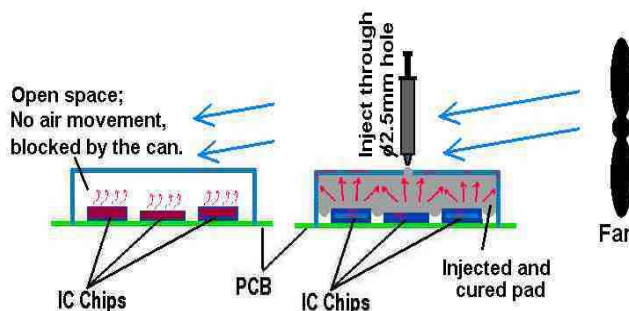


■ Application

- Inject into shielding can so as to double as heatsink
- Between heat source and chassis.
- Between CPU and heatsink.
- Between CD ROM drive and heat spreader
- Replacement for messy grease
- Can be dispensed using an automatic dispenser.
- Available in syringes or cans to suit the dispenser.



Dispense enough amount so that each bead conforms to differing gap between a chip and the lid. Spill-over does not short-circuit.



Fill a shielding to conduct heat efficiently from chips to shielding can, making the shielding can double as a heatsink.

■ Technical data

ITEM		VALUE	TEST METHOD
Material	Binder	Silicone	
	Filler	Alumina	
Mechanical properties after cure	Color	Gray	Visual
	Hardness (Shore 00)	50	ASTM D 2240
	Specific gravity (g/cm ³)	2.3	ASTM D 792
	Continuous usage temp. (°C)	-60 ~ +200	
Electrical properties	Dielectric constant	5.5	ASTM D 150
	Dielectric breakdown (kV AC)	>10	ASTM D 149
	Volume resistivity (ohm-meter)	>10 ¹²	ASTM D 257
Thermal conductivity 10psi (w/mK)		1.5	ASTM D 5470
Flame Rating		UL94 V0	

■ Usage Instructions

Mixing Ratio: 1:1

Cure time: Less than 5 min at 100°C, 6.5 min at 85°C, or in 12 hours at room temp.

(Request cure time at a specific temperature)

Shrinkage after cure: Less than 0.01%

Mix A and B parts well. Dispense on a clean IC chip and assemble a heatsink or other mating surface on top. Cure in a heat tunnel for 5 min at 105°C, 6.5 min at 85°C or let it stand for 12 hours at room temperature.

Or inject and fill directly into a shielding can with air escape and cure.

Or when used as a thermal pad between heat source and chassis, dispense sufficient amount on top the heat source, and let the chassis push down the gel and let it cure. Gel conforms to ideal thicknesses. This eliminates the need for multiple pads with various thicknesses. Can be removed when service is required.

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